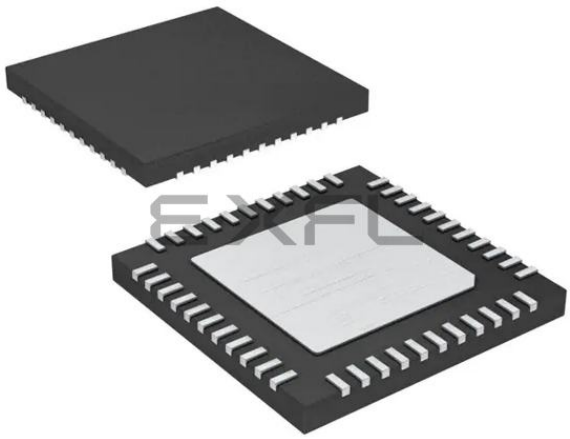
Microchip Technology - DSPIC33EP256MC504T-I/ML Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

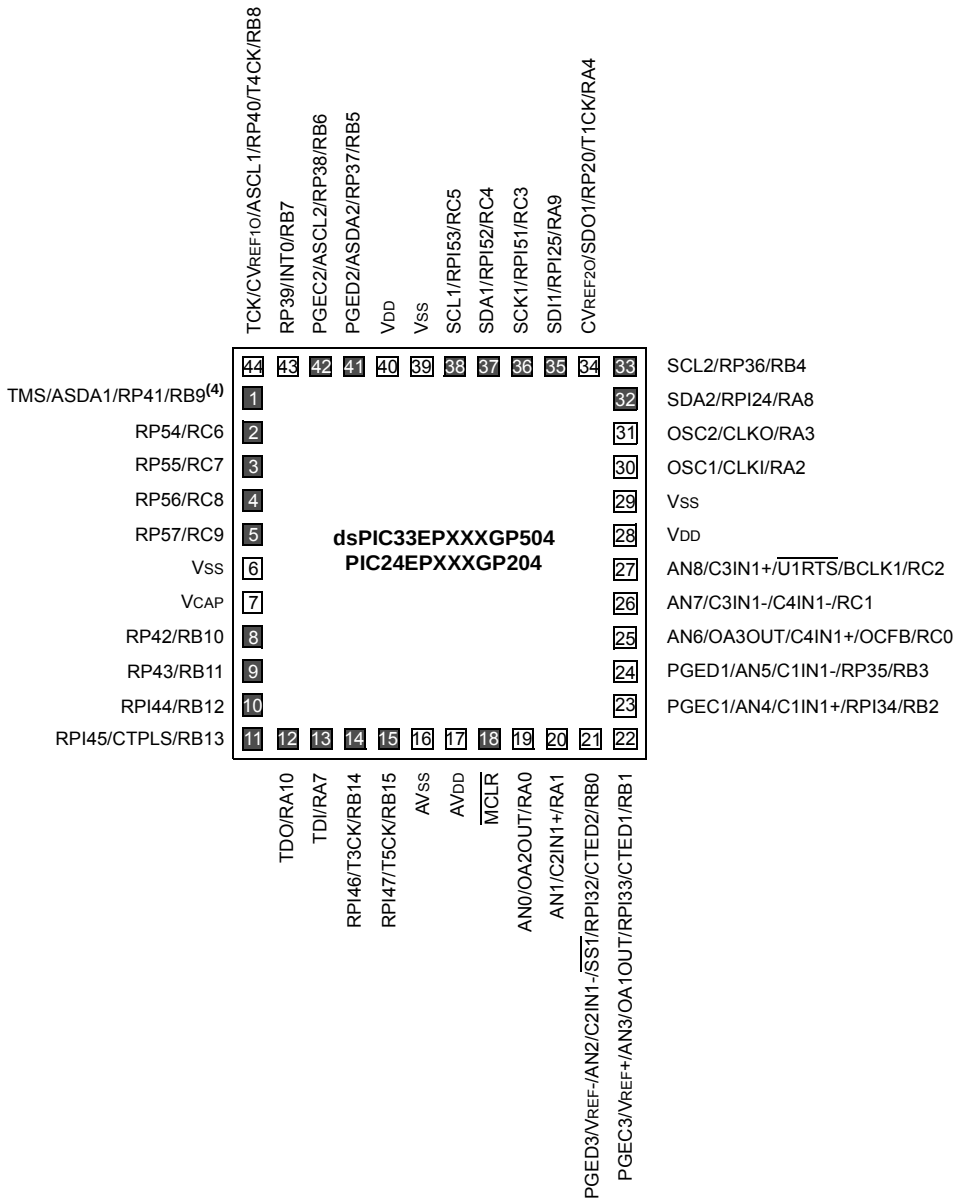
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc504t-i-ml

Pin Diagrams (Continued)

44-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

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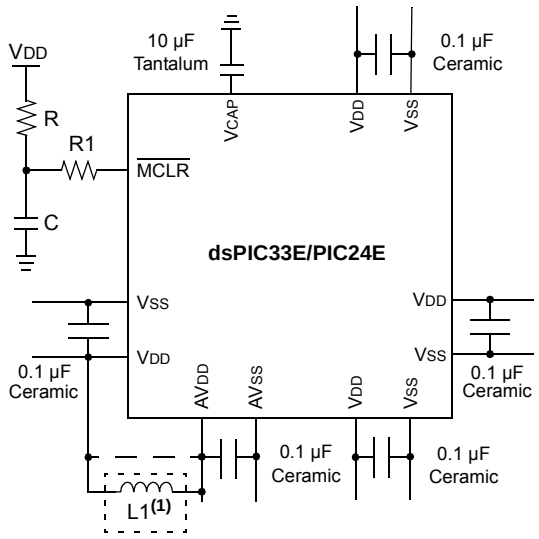
FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 1 Ohm) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 30.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 27.3 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

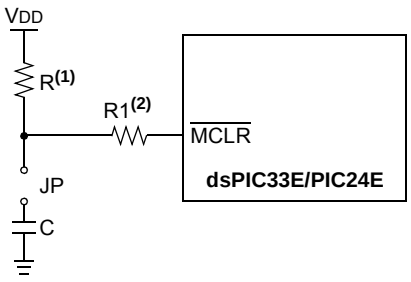
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

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TABLE 4-5: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXGP50X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
INTCON1	08C0	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	08C2	GIE	DISI	SWTRAP	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	8000
INTCON3	08C4	—	—	—	—	—	—	—	—	—	—	DAE	DOOVR	—	—	—	—	0000
INTCON4	08C6	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SGHT	0000
INTTREG	08C8	—	—	—	—	ILR<3:0>				VECNUM<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
QEI1 – QEI1 Position Counter Compare(2)	66	58	0x000088	IFS3<10>	IEC3<10>	IPC14<10:8>
Reserved	67-72	59-64	0x00008A-0x000094	—	—	—
U1E – UART1 Error Interrupt	73	65	0x000096	IFS4<1>	IEC4<1>	IPC16<6:4>
U2E – UART2 Error Interrupt	74	66	0x000098	IFS4<2>	IEC4<2>	IPC16<10:8>
CRC – CRC Generator Interrupt	75	67	0x00009A	IFS4<3>	IEC4<3>	IPC16<14:12>
Reserved	76-77	68-69	0x00009C-0x00009E	—	—	—
C1TX – CAN1 TX Data Request(1)	78	70	0x000A0	IFS4<6>	IEC4<6>	IPC17<10:8>
Reserved	79-84	71-76	0x0000A2-0x0000AC	—	—	—
CTMU – CTMU Interrupt	85	77	0x0000AE	IFS4<13>	IEC4<13>	IPC19<6:4>
Reserved	86-101	78-93	0x0000B0-0x0000CE	—	—	—
PWM1 – PWM Generator 1(2)	102	94	0x0000D0	IFS5<14>	IEC5<14>	IPC23<10:8>
PWM2 – PWM Generator 2(2)	103	95	0x0000D2	IFS5<15>	IEC5<15>	IPC23<14:12>
PWM3 – PWM Generator 3(2)	104	96	0x0000D4	IFS6<0>	IEC6<0>	IPC24<2:0>
Reserved	105-149	97-141	0x0001D6-0x00012E	—	—	—
ICD – ICD Application	150	142	0x000142	IFS8<14>	IEC8<14>	IPC35<10:8>
JTAG – JTAG Programming	151	143	0x000130	IFS8<15>	IEC8<15>	IPC35<14:12>
Reserved	152	144	0x000134	—	—	—
PTGSTEP – PTG Step	153	145	0x000136	IFS9<1>	IEC9<1>	IPC36<6:4>
PTGWDT – PTG Watchdog Time-out	154	146	0x000138	IFS9<2>	IEC9<2>	IPC36<10:8>
PTG0 – PTG Interrupt 0	155	147	0x00013A	IFS9<3>	IEC9<3>	IPC36<14:12>
PTG1 – PTG Interrupt 1	156	148	0x00013C	IFS9<4>	IEC9<4>	IPC37<2:0>
PTG2 – PTG Interrupt 2	157	149	0x00013E	IFS9<5>	IEC9<5>	IPC37<6:4>
PTG3 – PTG Interrupt 3	158	150	0x000140	IFS9<6>	IEC9<6>	IPC37<10:8>
Reserved	159-245	151-245	0x000142-0x0001FE	—	—	—
Lowest Natural Order Priority						

Note 1: This interrupt source is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

2: This interrupt source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

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REGISTER 8-11: DMAPWC: DMA PERIPHERAL WRITE COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as '0'

bit 3 **PWCOL3:** DMA Channel 3 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

bit 2 **PWCOL2:** DMA Channel 2 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

bit 1 **PWCOL1:** DMA Channel 1 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

bit 0 **PWCOL0:** DMA Channel 0 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

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REGISTER 9-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	PLLDIV8
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
PLLDIV7	PLLDIV6	PLLDIV5	PLLDIV4	PLLDIV3	PLLDIV2	PLLDIV1	PLLDIV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8-0 **PLLDIV<8:0>:** PLL Feedback Divisor bits (also denoted as ‘M’, PLL multiplier)

111111111 = 513
•
•
•
000110000 = 50 (default)
•
•
•
000000010 = 4
000000001 = 3
000000000 = 2

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REGISTER 11-13: RPINR23: PERIPHERAL PIN SELECT INPUT REGISTER 23

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SS2R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **SS2R<6:0>:** Assign SPI2 Slave Select ($\overline{SS2}$) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 11-14: RPINR26: PERIPHERAL PIN SELECT INPUT REGISTER 26 (dsPIC33EPXXXGP/MC50X DEVICES ONLY)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	C1RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **C1RXR<6:0>:** Assign CAN1 RX Input (CRX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

NOTES:

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REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^2C slave)
Used in conjunction with the SCLREL bit.
1 = Enables software or receives clock stretching
0 = Disables software or receives clock stretching

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^2C master, applicable during master receive)
Value that is transmitted when the software initiates an Acknowledge sequence.
1 = Sends NACK during Acknowledge
0 = Sends ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I^2C master, applicable during master receive)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins and transmits ACKDT data bit. Hardware is clear at the end of the master Acknowledge sequence.
0 = Acknowledge sequence is not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^2C master)
1 = Enables Receive mode for I^2C. Hardware is clear at the end of the eighth bit of the master receive data byte.
0 = Receive sequence is not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^2C master)
1 = Initiates Stop condition on SDAx and SCLx pins. Hardware is clear at the end of the master Stop sequence.
0 = Stop condition is not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^2C master)
1 = Initiates Repeated Start condition on SDAx and SCLx pins. Hardware is clear at the end of the master Repeated Start sequence.
0 = Repeated Start condition is not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^2C master)
1 = Initiates Start condition on SDAx and SCLx pins. Hardware is clear at the end of the master Start sequence.
0 = Start condition is not in progress

Note 1: When performing master operations, ensure that the IPMIEN bit is set to '0'.

REGISTER 21-5: CxFIFO: ECANx FIFO STATUS REGISTER

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FBP5	FBP4	FBP3	FBP2	FBP1	FBP0
bit 15							bit 8

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FNRB5	FNRB4	FNRB3	FNRB2	FNRB1	FNRB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **FBP<5:0>:** FIFO Buffer Pointer bits

011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **FNRB<5:0>:** FIFO Next Read Buffer Pointer bits

011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

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REGISTER 21-26: CxTRmnCON: ECANx TX/RX BUFFER mn CONTROL REGISTER (m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI1	TXnPRI0
bit 15							bit 8

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm(1)	TXLARBm(1)	TXERRm(1)	TXREQm	RTRENm	TXmPRI1	TXmPRI0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 See Definition for bits<7:0>, Controls Buffer n

bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer TRBn is a transmit buffer
0 = Buffer TRBn is a receive buffer

bit 6 **TXABTm:** Message Aborted bit(1)
1 = Message was aborted
0 = Message completed transmission successfully

bit 5 **TXLARBm:** Message Lost Arbitration bit(1)
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent

bit 4 **TXERRm:** Error Detected During Transmission bit(1)
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQm:** Message Send Request bit
1 = Requests that a message be sent; the bit automatically clears when the message is successfully sent
0 = Clearing the bit to '0' while set requests a message abort

bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQ is set.

Note: The buffers, SID, EID, DLC, Data Field, and Receive Status registers are located in DMA RAM.

REGISTER 24-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER(1,2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCTS4	ADCTS3	ADCTS2	ADCTS1	IC4TSS	IC3TSS	IC2TSS	IC1TSS
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OC4CS	OC3CS	OC2CS	OC1CS	OC4TSS	OC3TSS	OC2TSS	OC1TSS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADCTS4:** Sample Trigger PTGO15 for ADC bit
1 = Generates Trigger when the broadcast command is executed
0 = Does not generate Trigger when the broadcast command is executed

bit 14 **ADCTS3:** Sample Trigger PTGO14 for ADC bit
1 = Generates Trigger when the broadcast command is executed
0 = Does not generate Trigger when the broadcast command is executed

bit 13 **ADCTS2:** Sample Trigger PTGO13 for ADC bit
1 = Generates Trigger when the broadcast command is executed
0 = Does not generate Trigger when the broadcast command is executed

bit 12 **ADCTS1:** Sample Trigger PTGO12 for ADC bit
1 = Generates Trigger when the broadcast command is executed
0 = Does not generate Trigger when the broadcast command is executed

bit 11 **IC4TSS:** Trigger/Synchronization Source for IC4 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 10 **IC3TSS:** Trigger/Synchronization Source for IC3 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 9 **IC2TSS:** Trigger/Synchronization Source for IC2 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 8 **IC1TSS:** Trigger/Synchronization Source for IC1 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 7 **OC4CS:** Clock Source for OC4 bit
1 = Generates clock pulse when the broadcast command is executed
0 = Does not generate clock pulse when the broadcast command is executed

bit 6 **OC3CS:** Clock Source for OC3 bit
1 = Generates clock pulse when the broadcast command is executed
0 = Does not generate clock pulse when the broadcast command is executed

bit 5 **OC2CS:** Clock Source for OC2 bit
1 = Generates clock pulse when the broadcast command is executed
0 = Does not generate clock pulse when the broadcast command is executed

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

2: This register is only used with the PTGCTRL OPTION = 1111 Step command.

TABLE 24-1: PTG STEP COMMAND FORMAT (CONTINUED)

bit 3-0	Step Command	OPTION<3:0>	Option Description
	PTGCTRL(1)	0000	Reserved.
		0001	Reserved.
		0010	Disable Step Delay Timer (PTGSD).
		0011	Reserved.
		0100	Reserved.
		0101	Reserved.
		0110	Enable Step Delay Timer (PTGSD).
		0111	Reserved.
		1000	Start and wait for the PTG Timer0 to match the Timer0 Limit Register.
		1001	Start and wait for the PTG Timer1 to match the Timer1 Limit Register.
		1010	Reserved.
		1011	Wait for the software trigger bit transition from low-to-high before continuing (PTGSWT = 0 to 1).
		1100	Copy contents of the Counter 0 register to the AD1CHS0 register.
		1101	Copy contents of the Counter 1 register to the AD1CHS0 register.
		1110	Copy contents of the Literal 0 register to the AD1CHS0 register.
		1111	Generate triggers indicated in the Broadcast Trigger Enable register (PTGBTE).
	PTGADD(1)	0000	Add contents of the PTGADJ register to the Counter 0 Limit register (PTGC0LIM).
		0001	Add contents of the PTGADJ register to the Counter 1 Limit register (PTGC1LIM).
		0010	Add contents of the PTGADJ register to the Timer0 Limit register (PTGT0LIM).
		0011	Add contents of the PTGADJ register to the Timer1 Limit register (PTGT1LIM).
		0100	Add contents of the PTGADJ register to the Step Delay Limit register (PTGSDLIM).
		0101	Add contents of the PTGADJ register to the Literal 0 register (PTGL0).
		0110	Reserved.
		0111	Reserved.
	PTGCOPY(1)	1000	Copy contents of the PTGHOLD register to the Counter 0 Limit register (PTGC0LIM).
		1001	Copy contents of the PTGHOLD register to the Counter 1 Limit register (PTGC1LIM).
		1010	Copy contents of the PTGHOLD register to the Timer0 Limit register (PTGT0LIM).
		1011	Copy contents of the PTGHOLD register to the Timer1 Limit register (PTGT1LIM).
		1100	Copy contents of the PTGHOLD register to the Step Delay Limit register (PTGSDLIM).
		1101	Copy contents of the PTGHOLD register to the Literal 0 register (PTGL0).
		1110	Reserved.
		1111	Reserved.

Note 1: All reserved commands or options will execute but have no effect (i.e., execute as a NOP instruction).

2: Refer to Table 24-2 for the trigger output descriptions.

3: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

TABLE 24-2: PTG OUTPUT DESCRIPTIONS

PTG Output Number	PTG Output Description
PTGO0	Trigger/Synchronization Source for OC1
PTGO1	Trigger/Synchronization Source for OC2
PTGO2	Trigger/Synchronization Source for OC3
PTGO3	Trigger/Synchronization Source for OC4
PTGO4	Clock Source for OC1
PTGO5	Clock Source for OC2
PTGO6	Clock Source for OC3
PTGO7	Clock Source for OC4
PTGO8	Trigger/Synchronization Source for IC1
PTGO9	Trigger/Synchronization Source for IC2
PTGO10	Trigger/Synchronization Source for IC3
PTGO11	Trigger/Synchronization Source for IC4
PTGO12	Sample Trigger for ADC
PTGO13	Sample Trigger for ADC
PTGO14	Sample Trigger for ADC
PTGO15	Sample Trigger for ADC
PTGO16	PWM Time Base Synchronous Source for PWM(1)
PTGO17	PWM Time Base Synchronous Source for PWM(1)
PTGO18	Mask Input Select for Op Amp/Comparator
PTGO19	Mask Input Select for Op Amp/Comparator
PTGO20	Reserved
PTGO21	Reserved
PTGO22	Reserved
PTGO23	Reserved
PTGO24	Reserved
PTGO25	Reserved
PTGO26	Reserved
PTGO27	Reserved
PTGO28	Reserved
PTGO29	Reserved
PTGO30	PTG Output to PPS Input Selection
PTGO31	PTG Output to PPS Input Selection

Note 1: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER (CONTINUED)

bit 1 **C2OUT:** Comparator 2 Output Status bit(2)

When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 0 **C1OUT:** Comparator 1 Output Status bit(2)

When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.

2: Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

FIGURE 30-19: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

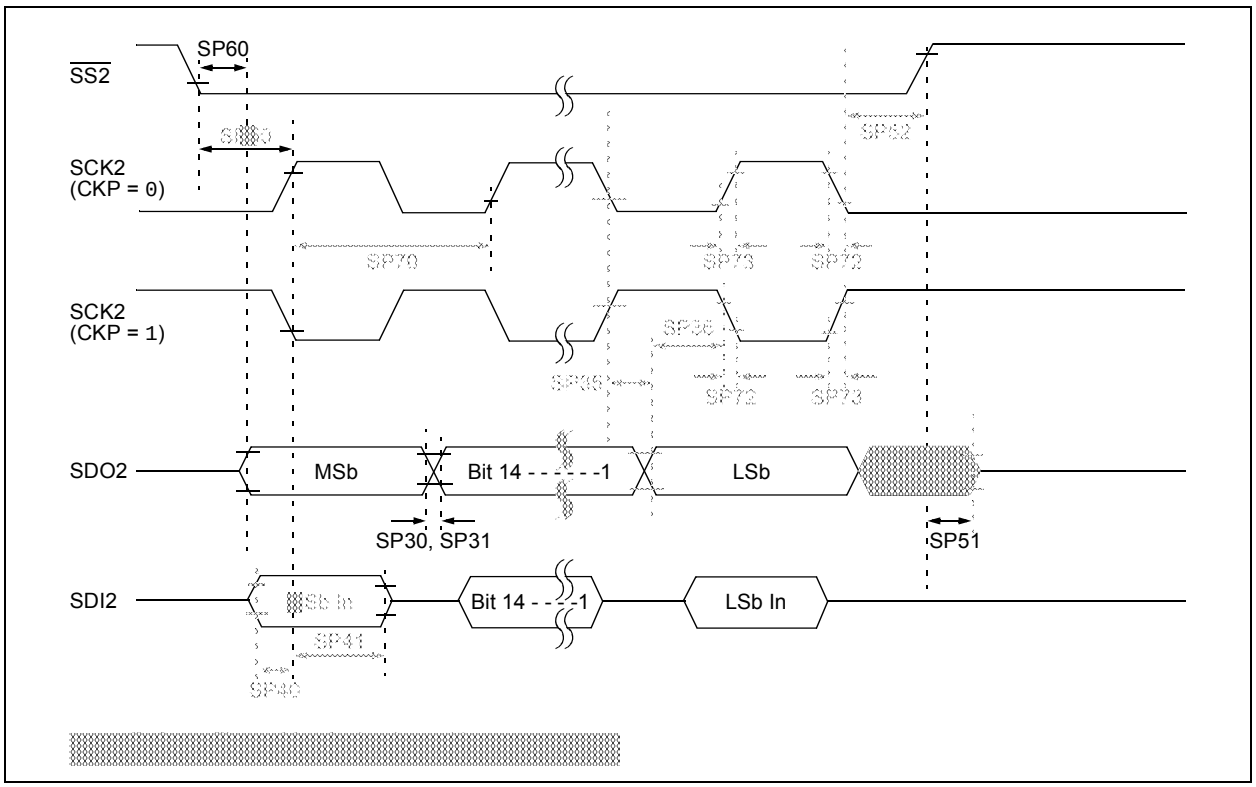

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TABLE 30-39: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
Op Amp DC Characteristics							
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio(3)	—	40	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage(3)	—	±5	—	mV	
CM43	VGAIN	Open-Loop Voltage Gain(3)	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 30-11
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 30-11
CM46	IOUT	Output Current	—	—	420	µA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	
CM49a	VOADC	Output Voltage Measured at OAx Using ADC(3,4)	AVSS + 0.077 AVSS + 0.037 AVSS + 0.018	— — —	AVDD – 0.077 AVDD – 0.037 AVDD – 0.018	V V V	IOUT = 420 µA IOUT = 200 µA IOUT = 100 µA
CM49b	VOUT	Output Voltage Measured at OAxOUT Pin(3,4,5)	AVSS + 0.210 AVSS + 0.100 AVSS + 0.050	— — —	AVDD – 0.210 AVDD – 0.100 AVDD – 0.050	V V V	IOUT = 420 µA IOUT = 200 µA IOUT = 100 µA
CM51	RINT1(6)	Internal Resistance 1 (Configuration A and B)(3,4,5)	198	264	317	Ω	Min = -40ºC Typ = +25ºC Max = +125ºC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.

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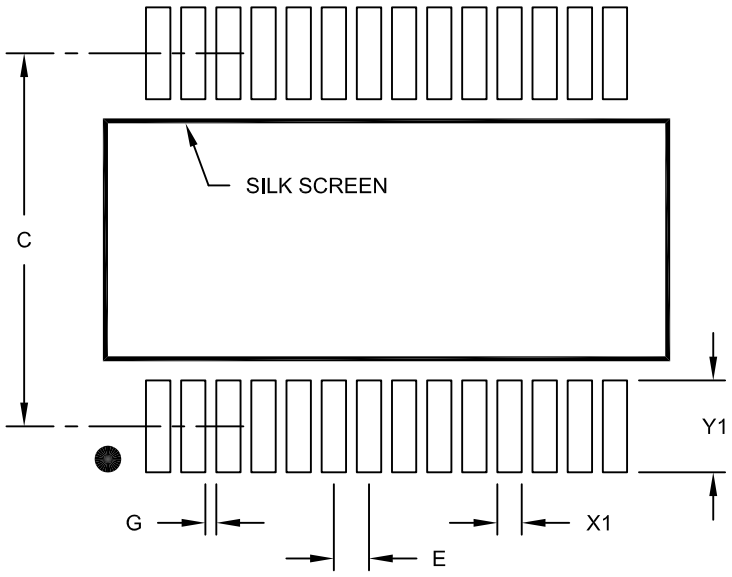
28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

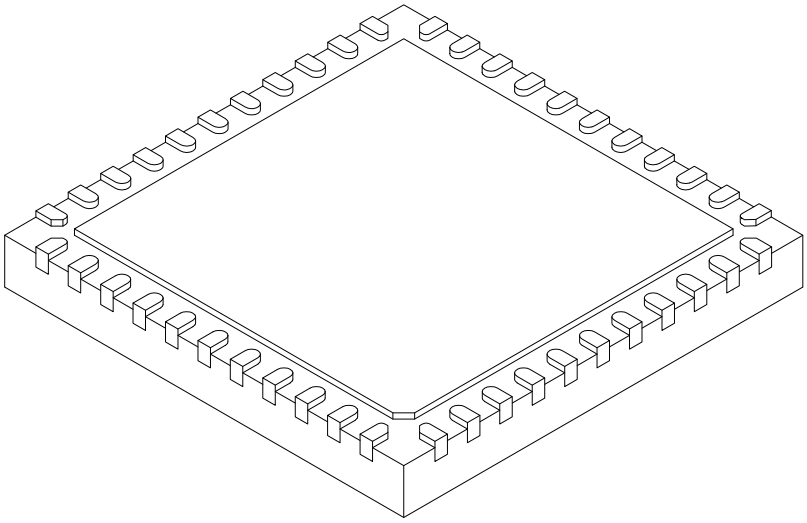
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

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